

WP934MD/LILGD T-1 (3mm) Bi-Level Circuit Board Indicator

DESCRIPTIONS

- The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode
- The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode

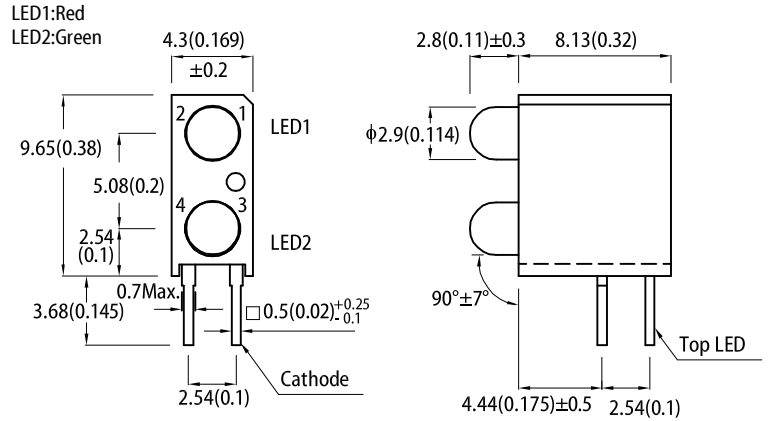
FEATURES

- Pre-trimmed leads for pc mounting
- Black case enhances contrast ratio
- High reliability life measured in years
- Housing UL rating: 94V-0
- Housing material: Type 66 nylon
- RoHS compliant

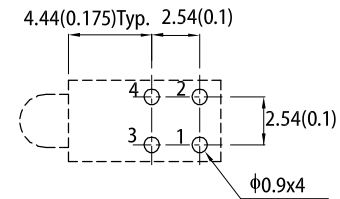
APPLICATIONS

- Status indicator
- Illuminator
- Signage applications
- Decorative and entertainment lighting
- Commercial and residential architectural lighting

PACKAGE DIMENSIONS



Recommended PCB Layout



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01^*)$ unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 2mA ^[2]		Viewing Angle ^[1]
			Min.	Typ.	2θ1/2
WP934MD/LILGD	■ High Efficiency Red (GaAsP/GaP)	Red Diffused	0.8	2	50°
			*0.5	*1.2	
	■ Green (GaP)	Green Diffused	1	3	50°
			*1	*3	

Notes:
 1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity / luminous flux: +/-15%.
 * Luminous intensity value is traceable to CIE127-2007 standards.

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I _F = 2mA	λ _{peak}	High Efficiency Red Green	627 565	-	nm
Dominant Wavelength I _F = 2mA	λ _{dom} ^[1]	High Efficiency Red Green	617 568	-	nm
Spectral Bandwidth at 50% Φ REL MAX I _F = 2mA	Δλ	High Efficiency Red Green	45 30	-	nm
Capacitance	C	High Efficiency Red Green	15 15	-	pF
Forward Voltage I _F = 2mA	V _F ^[2]	High Efficiency Red Green	1.7 1.9	2.1 2.25	V
Reverse Current (V _R = 5V)	I _R	High Efficiency Red Green	-	10 10	μA
Temperature Coefficient of λ _{peak} I _F = 2mA, -10°C ≤ T ≤ 85°C	TC _{λpeak}	High Efficiency Red Green	0.13 0.1	-	nm/°C
Temperature Coefficient of λ _{dom} I _F = 2mA, -10°C ≤ T ≤ 85°C	TC _{λdom}	High Efficiency Red Green	0.06 0.06	-	nm/°C
Temperature Coefficient of V _F I _F = 2mA, -10°C ≤ T ≤ 85°C	TC _V	High Efficiency Red Green	-1.9 -2	-	mV/°C

Notes:

- The dominant wavelength (λ_d) above is the setup value of the sorting machine. (Tolerance λ_d : ±1nm.)
- Forward voltage: ±0.1V.
- Wavelength value is traceable to CIE127-2007 standards.
- Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

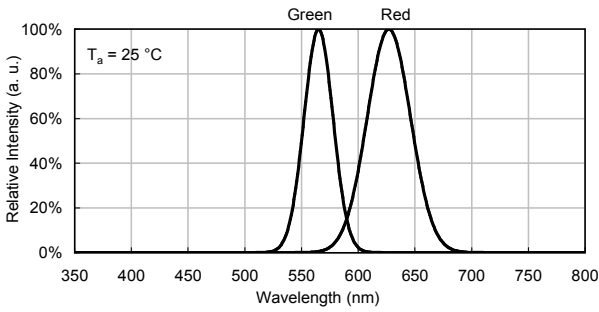
Parameter	Symbol	Value		Unit
		High Efficiency Red	Green	
Power Dissipation	P _D	75	62.5	mW
Reverse Voltage	V _R	5	5	V
Junction Temperature	T _j	125	110	°C
Operating Temperature	T _{op}	-40 to +85		°C
Storage Temperature	T _{stg}	-40 to +85		°C
DC Forward Current	I _F	30	25	mA
Peak Forward Current	I _{FM} ^[1]	160	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	8000	V
Thermal Resistance (Junction / Ambient)	R _{th JA} ^[2]	680	680	°C/W
Thermal Resistance (Junction / Solder point)	R _{th JS} ^[2]	450	460	°C/W
Lead Solder Temperature ^[3]		260°C For 3 Seconds		
Lead Solder Temperature ^[4]		260°C For 5 Seconds		

Notes:

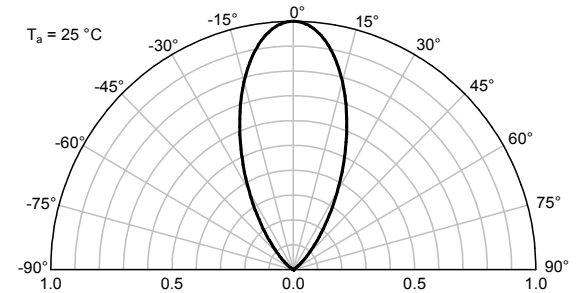
- 1/10 Duty Cycle, 0.1ms Pulse Width.
- R_{th JA}, R_{th JS} Results from mounting on PC board FR4 (pad size ≥ 16 mm² per pad).
- 2mm below package base.
- 5mm below package base.
- Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

TECHNICAL DATA

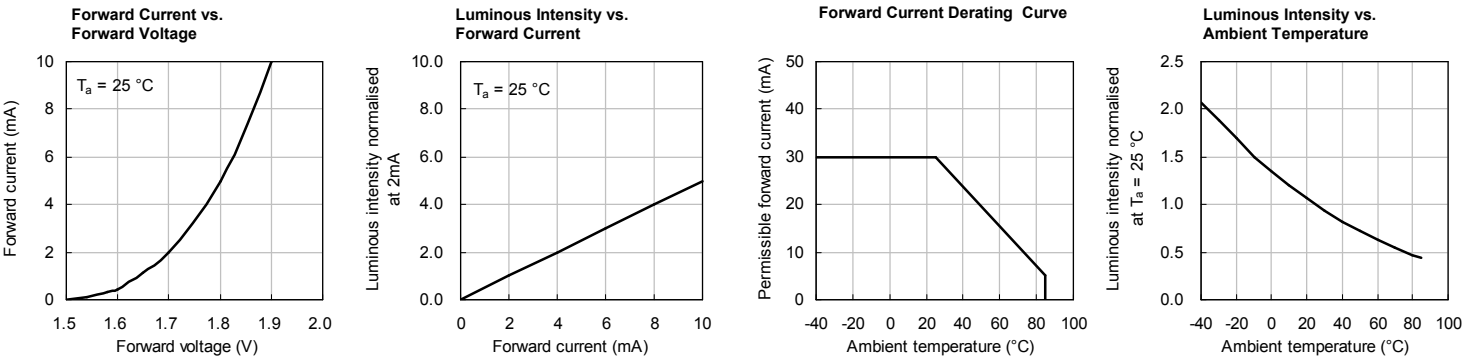
RELATIVE INTENSITY vs. WAVELENGTH



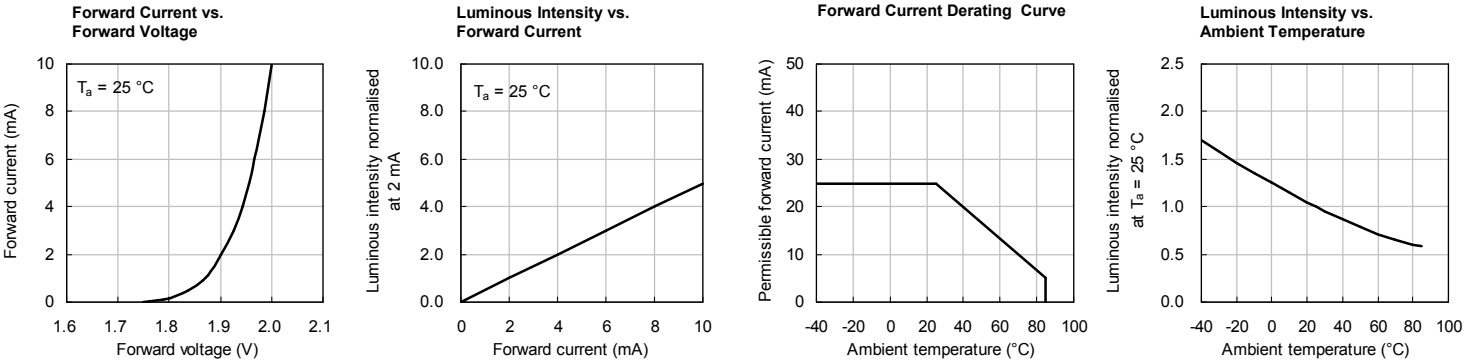
SPATIAL DISTRIBUTION



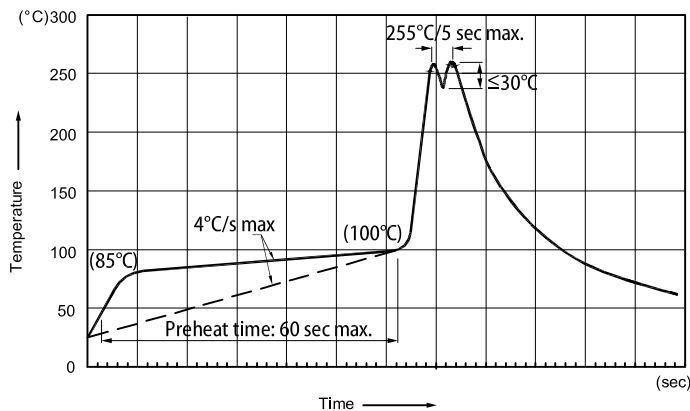
HIGH EFFICIENCY RED



GREEN



RECOMMENDED WAVE SOLDERING PROFILE



Notes:

1. Recommend pre-heat temperature of $105\text{ }^\circ\text{C}$ or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260\text{ }^\circ\text{C}$.
2. Peak wave soldering temperature between $245\text{ }^\circ\text{C} \sim 255\text{ }^\circ\text{C}$ for 3 sec (5 sec max).
3. Do not apply stress to the epoxy resin while the temperature is above $85\text{ }^\circ\text{C}$.
4. Fixtures should not incur stress on the component when mounting and during soldering process.
5. SAC 305 solder alloy is recommended.
6. No more than one wave soldering pass.